

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) An electronic microcircuit module including a substrate, at least one contact area on a first face of this substrate, a second face of this substrate capable of accommodating an integrated circuit, characterised in that it includes a parallelepiped shape, a first adhesive means to retain a first face of a mask in position against the second face of the substrate, the mask delimiting the parallelepiped being perforated to form a window around the integrated circuit and a second adhesive means dispensed on a second face of the mask.
2. (Original) The module according to claim 1, characterised in that the mask is made from a material identical to that of a card provided to receive the module, for example from a polymer of polyester or polyvinyl chloride type.
3. (Previously presented) The module according to claim 1, characterised in that the mask has a thickness, defined with regard to the second face of the substrate on which it is mounted, greater than the height of the integrated circuit.
4. (Previously presented) The module according to claim 1, characterised in that the first adhesive means enables the integrated circuit to be retained on the substrate.

5. (Currently amended) A method for conditioning an electronic microcircuit module, characterised in that it includes the following stages consisting of

creating a contact area on a first face of a substrate tape,

arranging a first adhesive means between a second face of the substrate and a first face of a mask tape, to keep the mask in position against the second face,

perforating the mask tape so that a mask window is facing the contact area, and

arranging a second adhesive means on the second face of the mask, ~~and~~

~~separating the individual module in the form of a parallelepiped.~~

6. (Original) The method according to claim 5, characterised in that it includes an additional stage consisting of:

choosing a mask in a material identical to that of a card on which the module is to be mounted.

7. (Previously presented) The method according to claim 5, characterised in that the mask has the form of a tape including several windows which are laminated on a support including several contact area before separation into individual units.

8. (Previously presented) The method according to claim 5, characterised in that the stage consisting in retaining the

mask in position against the second face of the substrate includes an operation consisting of:

laminating the first adhesive means on this second face of the substrate.

9. (Previously presented) The method according to claim 5, characterised in that the stage consisting in arranging an adhesive means on the mask includes an operation consisting of

depositing the adhesive means on the mask, and then

perforating this mask before laminating it against the second face of the substrate.

10. (Previously presented) The method according to claim 5, characterised in that it includes a subsequent stage consisting in gluing an integrated circuit to the second face of the substrate, on the first adhesive means.

11. (Previously presented) The method according to claim 5, characterised in that it includes a stage consisting of:

gluing the mask equipped with an electronic circuit to the bottom of a card recess.

12. (Original) The method according to claim 11, characterised in that the stage consisting in gluing the mask to the recess includes an operation consisting of:

depositing cyanoacrylate glue between the mask and the bottom of the recess.

13. (Original) The method according to claim 11, characterised in that the stage consisting in gluing the mask into the recess includes an operation consisting of:

soldering by emission of ultrasound waves.

14. (New) The method according to claim 5 further comprising separating the individual module in the form of a parallelepiped.